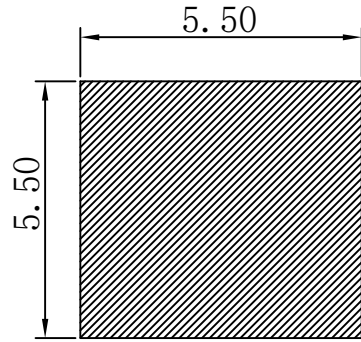
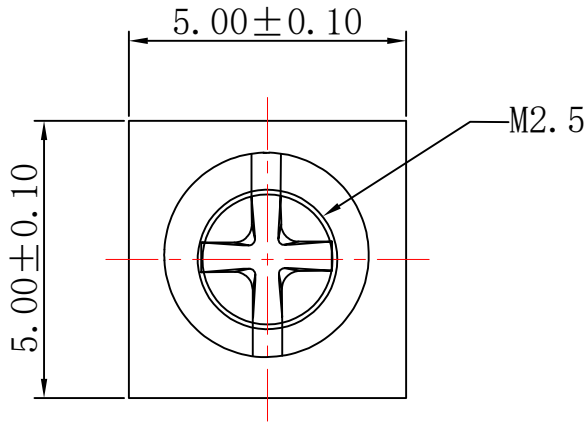


RoHS

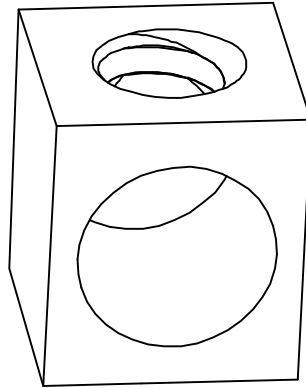
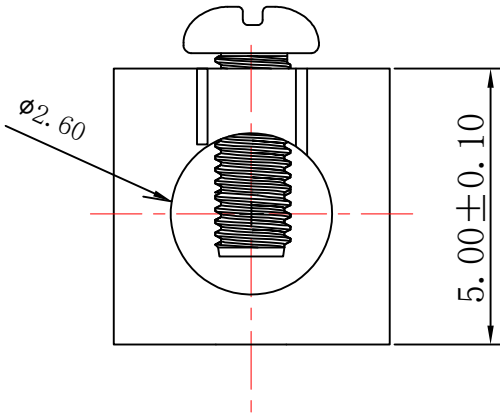
REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	新版发行			2025.03.19



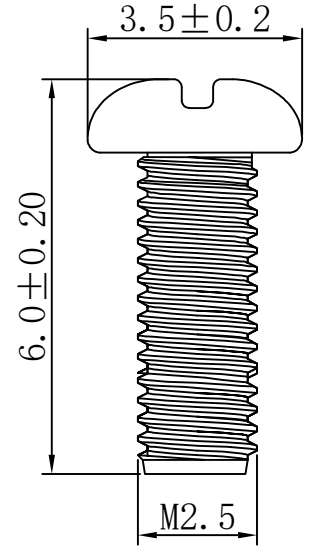
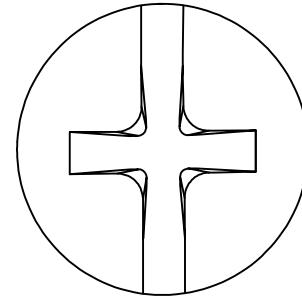
PCB LAYOUT

技术要求:

- 1.打铜底0.5-1 μ m,镍2-2.5 μ m, 镀镍。
- 2.铆好后不得有松动现象。
- 3.插脚尖部符合可焊性要求。
- 4.螺纹需符合通止规/止针要求。
- 5.螺纹扭矩: 0.4Nm.
- 6.额定电流: 20A.



3D VIEW



>30.±0.4	X.°±
6-30±0.3	.X°±
0-6±0.2	.XX°±
ANGLES±1°	.XXX°±
UNITS:	mm

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PART NO: TS7050050-0500		XFCN 兴飞连接器		
TITLE: PCB SOLDERING TERMINAL		0769-82001899		
		www.xfconn.com		
		DWG NO: /		
APPD	Chen ZhiQiang	VIEW		
CHKD	Liu Wei	SCALE	SHEET	REV
DRAW	Chen HongJiang	SCALE	SHEET	REV
DATE	2025.03.19	NONE	1/1	A1

序号	名称	零件编号	材质	数量
1	插脚		H62 (Y2)	1